

Michael Lane

List of Publications by Year in descending order

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12
papers

633
citations

1163117

8
h-index

1281871

11
g-index

12
all docs

12
docs citations

12
times ranked

512
citing authors

#	ARTICLE	IF	CITATIONS
1	Gold-titania interface toughening and thermal conductance enhancement using an organophosphonate nanolayer. Applied Physics Letters, 2013, 102, 201605.	3.3	15
2	Atomistic fracture energy partitioning at a metal-ceramic interface using a nanomolecular monolayer. Physical Review B, 2011, 83, .	3.2	8
3	Mechanical Scaling Trends and Methods to Improve Reliability of Packaged Interconnect Structures. Materials Research Society Symposia Proceedings, 2009, 1158, 1.	0.1	0
4	Annealing-induced interfacial toughening using a molecular nanolayer. Nature, 2007, 447, 299-302.	27.8	118
5	Interface Fracture. Annual Review of Materials Research, 2003, 33, 29-54.	9.3	92
6	Interfacial Relationships in Microelectronic Devices. Materials Research Society Symposia Proceedings, 2003, 766, 911.	0.1	19
7	Plasticity contributions to interface adhesion in thin-film interconnect structures. Journal of Materials Research, 2000, 15, 2758-2769.	2.6	164
8	Adhesion and reliability of copper interconnects with Ta and TaN barrier layers. Journal of Materials Research, 2000, 15, 203-211.	2.6	165
9	Subcritical Debonding of Multilayer Interconnect Structures: Temperature and Humidity Effects. Materials Research Society Symposia Proceedings, 1999, 563, 251.	0.1	9
10	Effect of Nitrogen Content on Interfacial Adhesion of the Ta/SiO ₂ Interface. Materials Research Society Symposia Proceedings, 1999, 564, 281.	0.1	2
11	Adhesion Measurement of Interfaces in Multilayer Interconnect Structures. Materials Research Society Symposia Proceedings, 1997, 473, 3.	0.1	29
12	Progressive Debonding of Multilayer Interconnect Structures. Materials Research Society Symposia Proceedings, 1997, 473, 21.	0.1	12